C122F1, C122B1

Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed primarily for full-wave ac control applications, such as motor controls, heating controls and power supplies; or wherever half-wave silicon gate-controlled, solid-state devices are needed.

- Glass Passivated Junctions and Center Gate Fire for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 200 Volts
- Device Marking: Logo, Device Type, e.g., C122F1, Date Code

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage ⁽¹⁾ (T _J = 25 to 100°C, Sine Wave, 50 to 60 Hz; Gate Open) C122F1	V _{DRM} , V _{RRM}	50	Volts
C122B1		200	
On-State RMS Current (180° Conduction Angles; T _C = 75°C)	IT(RMS)	8.0	Amps
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T _C = 75°C)	ITSM	90	Amps
Circuit Fusing Considerations (t = 8.3 ms)	l ² t	34	A ² s
Forward Peak Gate Power (Pulse Width = 10 μs, T _C = 70°C)	PGM	5.0	Watts
Forward Average Gate Power (t = 8.3 ms, T _C = 70°C)	P _{G(AV)}	0.5	Watt
Forward Peak Gate Current (Pulse Width = 10 μs, T _C = 70°C)	I _{GM}	2.0	Amps
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

(1) VDRM and VRRM for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

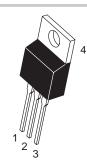


ON Semiconductor

http://onsemi.com

SCRs 8 AMPERES RMS 50 thru 200 VOLTS





TO-220AB CASE 221A STYLE 3

PIN ASSIGNMENT			
1	Cathode		
2	Anode		
3	Gate		
4	Anode		

ORDERING INFORMATION

Device	Package	Shipping
C122F1	TO220AB	500/Box
C122B1	TO220AB	500/Box

C122F1, C122B1

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.8	°C/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

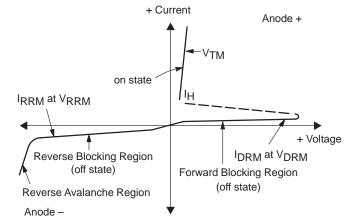
ELECTRICAL CHARACTERISTICS (To = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS		•			•	•
Peak Repetitive Forward or Reverse Blocking Current (VAK = Rated VDRM or VRRM, Gate Open)	T _C = 25°C T _C = 125°C	IDRM, IRRM	_	_	10 0.5	μA mA
ON CHARACTERISTICS						
Peak On–State Voltage(1) (I _{TM} = 16 A Peak, T _C = 25°C)		VTM	_	_	1.83	Volts
Gate Trigger Current (Continuous dc) (V _{AK} = 12 V, R _L = 100 Ohms)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	^I GT	_	_	25 40	mA
Gate Trigger Voltage (Continuous dc) (V _{AK} = 12 V, R _L = 100 Ohms)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	VGТ	_	_	1.5 2.0	Volts
Gate Non-Trigger Voltage (Continuous dc) (V _{AK} = 12 V, R _L = 100 Ohms, T _C = 125°C)	V _{GD}	0.2	_	_	Volts	
Holding Current (VAK = 12 Vdc, Initiating Current = 200 mA, Gate Oper	Ιн	_	_	30 60	mA	
Turn-Off Time (V_D = Rated V_{DRM}) (I_{TM} = 8 A, I_R = 8 A)		^t q	_	50	_	μs
DYNAMIC CHARACTERISTICS						
Critical Rate–of–Rise of Off–State Voltage (V _{AK} = Rated V _{DRM} , Exponential Waveform, Gate Open, T _C = 100°C)		dv/dt	_	50	_	V/µs

⁽¹⁾ Pulse Test: Pulse Width \leq 1 ms, Duty Cycle \leq 2%.

Voltage Current Characteristic of SCR

Symbol	Parameter
VDRM	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
I _{RRM}	Peak Reverse Blocking Current
V _{TM}	Peak On State Voltage
lΗ	Holding Current



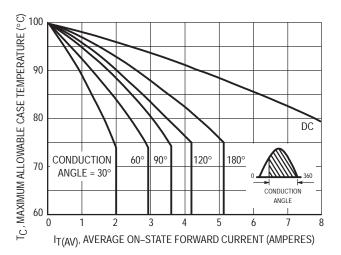


Figure 1. Current Derating (Half-Wave)

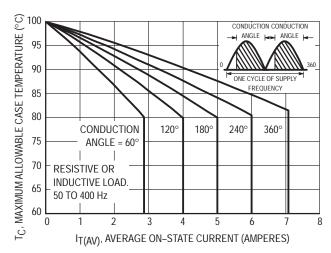


Figure 2. Current Derating (Full-Wave)

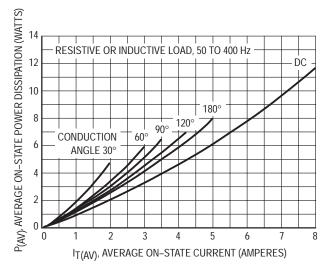


Figure 3. Maximum Power Dissipation (Half-Wave)

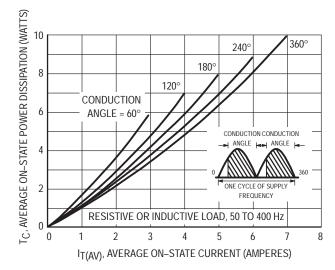
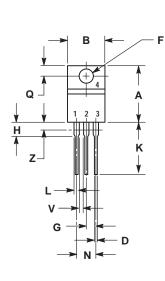
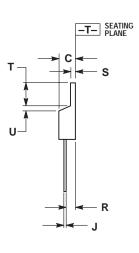


Figure 4. Maximum Power Dissipation (Full-Wave)

PACKAGE DIMENSIONS

TO-220AB CASE 221A-07 **ISSUE Z**





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 3:

PIN 1. CATHODE

ANODE 2.

GATE ANODE

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Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center 4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-8549

Phone: 81-3-5740-2745 Email: r14525@onsemi.com

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